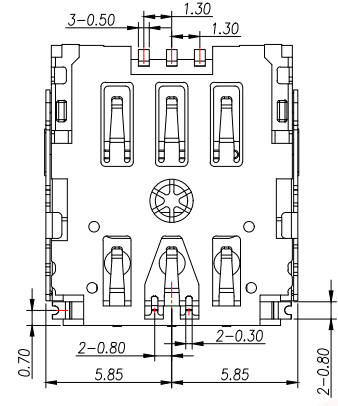
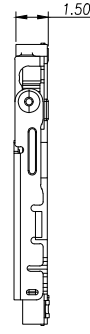
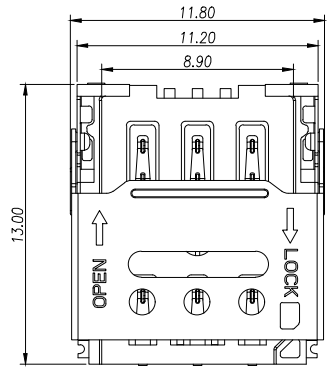
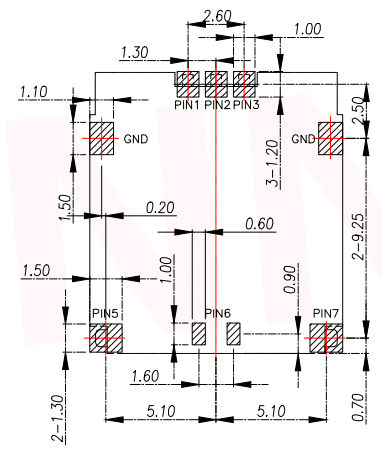
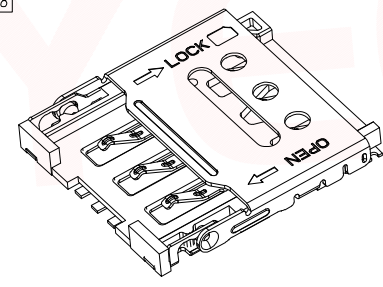
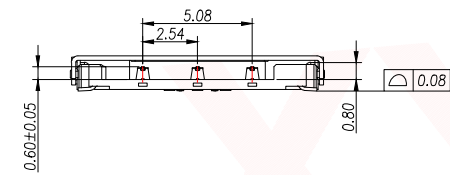


REV.	Q'TY	ECN. NO.	APR.	DATE

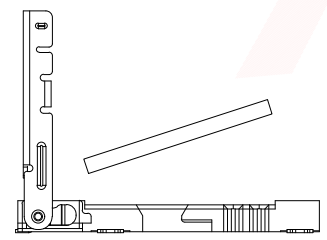


NOTES:
 1.MATERIAL:
 1-1 HOUSING:THERMOPLASTIC,UL94 V-0. COLOR:BLACK
 1-2 SHELL:STAINLESS STEEL T=0.20mm
 1-3 CONTACT:COPPER ALLOY T=0.15mm
 2.FINISH:
 2-1 CONTACT: 1U" AU MIN. ON CONTACT AREA
 GOLD FLASH ON SOLDER AREA
 50u" NI MIN. UNDERPLATING OVER ALL

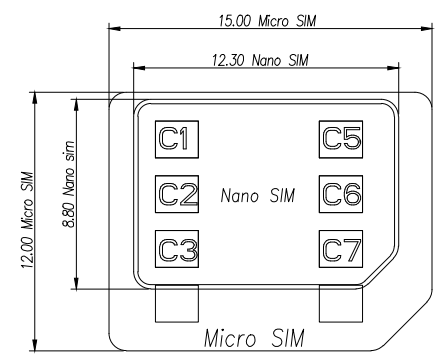


SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)
 RECOMMENDED MATAL MASK T=0.12mm



STEP 1 INSERT Micro-SIM CARD
 STEP 2 PUSH THE SHELL
 STEP 3 FINISH



DIMENSION IN mm		TOLERANCE UNLESS OTHERWISE SPECIFIED		APR. Alex		TITLE: 1.5H 6PIN HINGE NANO SIM CARD CONNECTOR	
.X±0.35	X.*± 5'	.XX±0.25	.X*± 3'	CHK. Jack	DWG NO. SIM303-FWB7AH1.5		
.XXX±0.15	.XX*± 1'	DRA. Can	PROJ.		CUSTOMER DRAWING		
SIZE A4	SCALE 1:1	SHEET 1/1	REV. A				

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